

ABSTRACT

A package structure of an image sensor for electrically connecting to a printed circuit board includes a transparent layer and an image sensing chip. A plurality of signal input terminals and signal output terminals are formed on the transparent layer. The signal output terminals are used for electrically connecting the transparent layer to the printed circuit board. A plurality of electrical circuits are formed on the image sensing chip. Each of the electrical circuits is formed with bonding pads and is electrically connected to the transparent layer by way of flip chip bonding. The bonding pads are electrically connected to the signal input terminals of the transparent layer. The image sensing chip receives image signals via the transparent layer, converts the image signals into electrical signals, and transmits the electrical signals from the signal output terminals of the transparent layer to the printed circuit board. Thus, the packaging costs of the image sensor can be lowered and the packaging processes of the image sensor can be simplified. A method for packaging the image sensor is also provided.